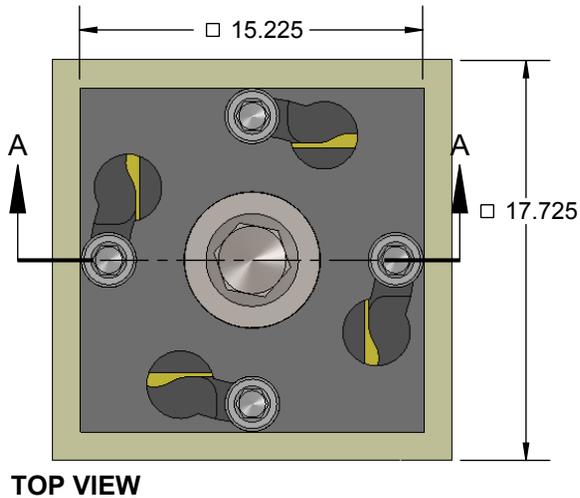


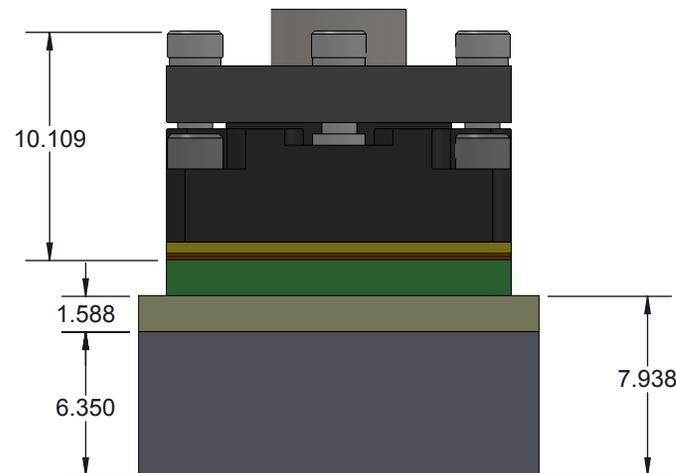
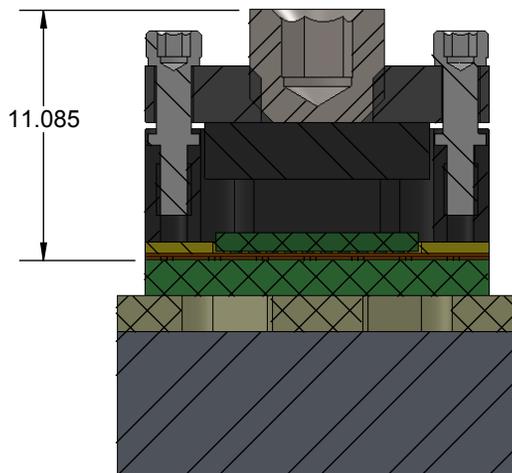
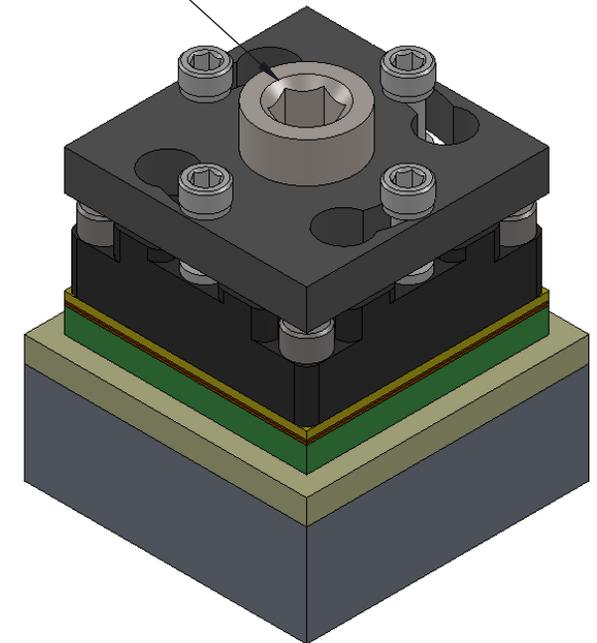
# GHz BGA Socket - Direct mount, solderless

## Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



Recommended torque = 1-2 in-lbs



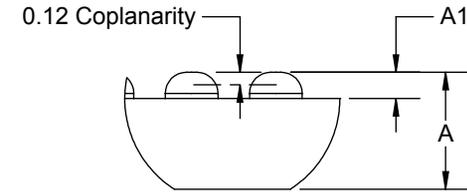
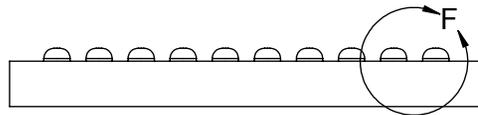
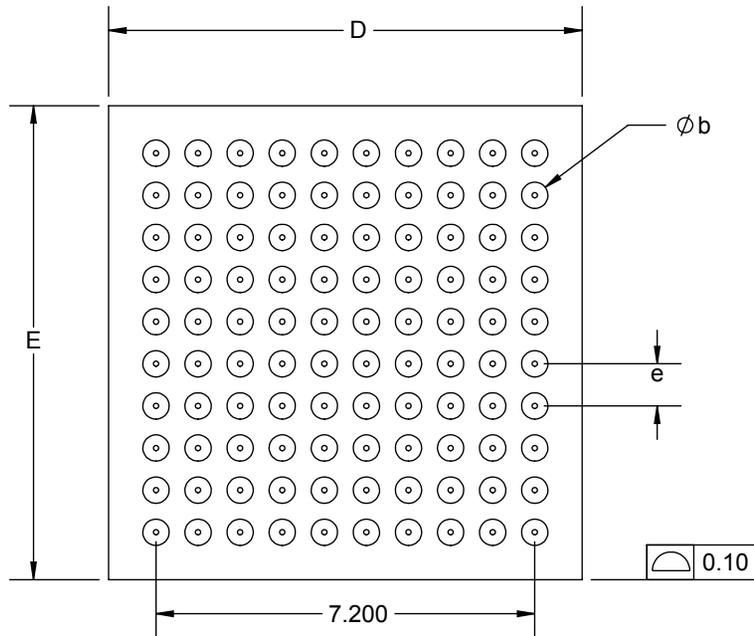
## Description: GT-BGA for 9x9mm 0.8mm pitch BGA100

Primary dimension units are millimeters. Secondary dimension units are [inches]. Weight is in grams.

Tolerances: Hole diameters  $\pm 0.0254\text{mm}$  [ $\pm 0.001$ "]. Pitches (from true position)  $\pm 0.0762\text{mm}$  [ $\pm 0.003$ "]. substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.127\text{mm}$  [ $\pm 0.005$ "] unless stated otherwise. Materials and specifications are subject to change without notice.

 <b>GT-BGA-2000 Drawing</b> Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 11.89	STATUS: Released ENG: S. Huang FILE: GT-BGA-2000	SHEET: 1 OF 4 DRAWN BY: S. Huang DATE: 11/4/14	REV. A SCALE: 3:1





**DETAIL F**  
**SCALE 14 : 1**

DIM	MIN	MAX
A	---	1.4
A1	0.25	---
b	0.45	0.55
D	9 BSC	
E	9 BSC	
e	Pin count: 100	

Dimensions are in millimeters.

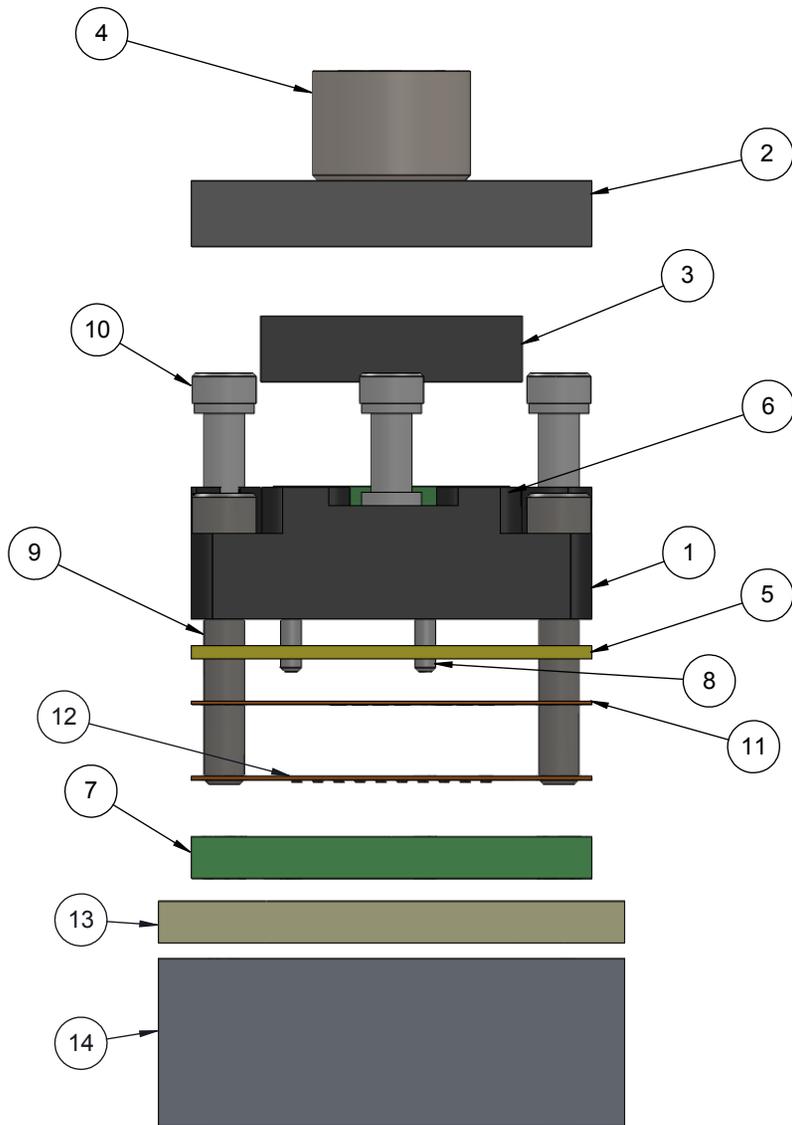
1. Interpret dimensions and tolerances per ASME Y14.5M-1994.
2. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
3. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
4. Parallelism measurement shall exclude any effect of mark on top surface of package.

### Description: Compatible Device

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

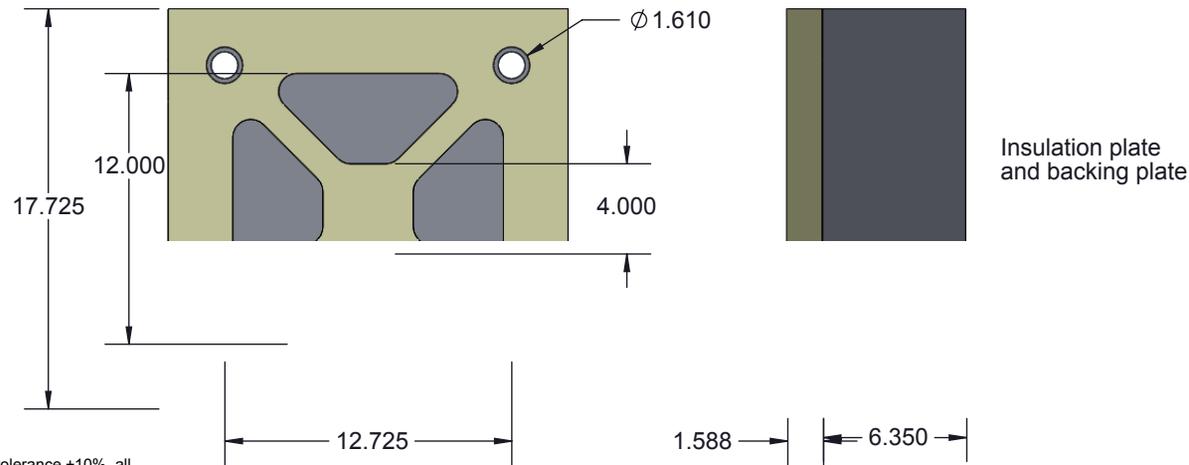
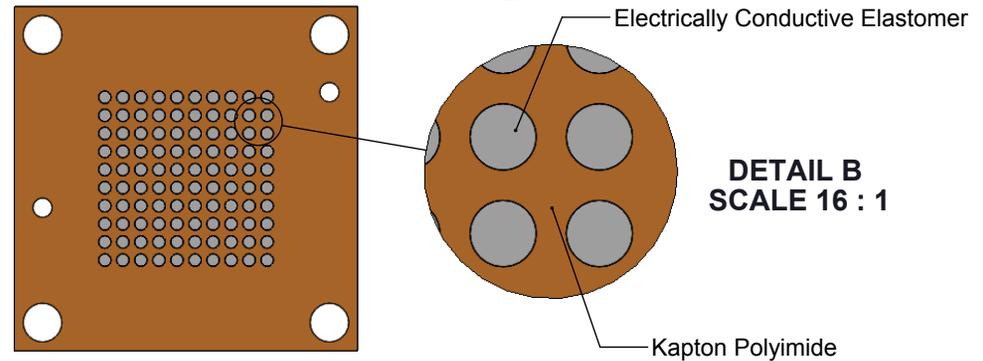
**Tolerances:** Hole diameters  $\pm 0.03\text{mm}$  [ $\pm 0.001''$ ], Pitches (from true position)  $\pm 0.025\text{mm}$  [ $\pm 0.001''$ ], substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.13\text{mm}$  [ $\pm 0.005''$ ] unless stated otherwise. Materials and specifications are subject to change without notice.

 <b>GT-BGA-2000 Drawing</b> Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 11.89	STATUS: Released ENG: S. Huang FILE: GT-BGA-2000	SHEET: 3 OF 4 DRAWN BY: S. Huang DATE: 11/4/14	REV. A SCALE: 7:1



ITEM NO.	DESCRIPTION	Material
1	Socket Base	7075-T6 Aluminum Alloy
2	Socket Lid	7075-T6 Aluminum Alloy
3	Compression Plate	7075-T6 Aluminum Alloy
4	Compression Screw M6x1	Stainless Steel (18-8)
5	IC Guide	Torlon 4203
6	BGA100 9x9mm 0.8mm pitch 10x10 array	High Temp FR4
7	Test PCB	FR4 High temp
8	Dowel Pin, 1/32" x 3/16", SS	Chrome Stainless Steel
9	#0-80 X .375 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel
10	#0-80 Shoulder Screw, 0.090" thread length	Stainless Steel (303)
11	Ball Guide	Kapton Polyimide
12	GT Elastomer 9x9mm IC 0.8mm pitch 10x10 array	Conductive Elastomer
13	Insulation Plate	FR4 High temp
14	Backing Plate, 17.73 X 17.73	7075-T6 Aluminum Alloy

**Elastomer Carrier with conductive elastomer**  
Scale 2:1



**Description: Socket, Elastomer Carrier**

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters  $\pm 0.03\text{mm}$  [ $\pm 0.001"$ ], Pitches (from true position)  $\pm 0.025\text{mm}$  [ $\pm 0.001"$ ], substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.13\text{mm}$  [ $\pm 0.005"$ ] unless stated otherwise. Materials and specifications are subject to change without notice.

 <b>GT-BGA-2000 Drawing</b> Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 11.89	STATUS: Released	SHEET: 4 OF 4	REV. A
		ENG: S. Huang	DRAWN BY: S. Huang	SCALE: 3.5:1
		FILE: GT-BGA-2000	DATE: 11/4/14	